

Addendum

Presenters Changed

Day-1, May 16, Poster Session, TuP-29

"Femtosecond laser ablation of Zr-based bulk metallic glasses"

T. Sano, Osaka University, Japan

→ K. Takahashi, Osaka University, Japan

Day-1, May 16, Poster Session, TuP-30

"Femtosecond laser synthesis of the high-pressure phases of titanium"

T. Sano, Osaka University, Japan

→ K. Takahashi, Osaka University, Japan

Day-2, May 17, HPL-03 Material Removal, We3-14

"Process development and control for laser drilled and shaped holes in turbine components"

E. W. Kreutz, Lehrstuhl für Lasertechnik RWTH-Aachen, Germany

→ A. Horn, Lehrstuhl für Lasertechnik RWTH-Aachen, Germany

Day-3, May 18, HPL-08 Latest Novel Processing, #Th1-15, Invited Talk

"Enhancing laser system flexibility with the combi-head for cutting and joining"

D. Petring, Fraunhofer-Institute für Laser Technology, Germany

→ R. Poprawe, Fraunhofer-Institute für Laser Technology, Aachen, President of the German Scientific Laser Association WLT, Germany

Day-3, May 18, HPL-09 Laser System, #Th1-16

"SIRILAS - the new standard of laser diode for high volume applications"

A. Schmitt, Opto Semiconductors GmbH, Germany

→ G. Okada, Spectronix Corporation, Japan

Day-3, May 18, HPL-12 Surface Treatment 3, #Th4-8, Invited Talk

"Laser metal deposition – A powerful tool for turb machinery"

E. W. Kreutz, Lehrstuhl für Lasertechnik RWTH-Aachen, Germany

→ J. Gottmann, Lehrstuhl für Lasertechnik RWTH-Aachen, Germany

Cancellation

Day-2, May 17, Poster Session, WeP-22

"Femtosecond laser fabrication of tungsten microspike-arrays for micro-emitter" (T. Sano) has been cancelled as of May 13.

Day-3, May 18, HPL-12 Surface Treatment 3, #Th4-10

"Mo-Si-B multiple phases coating produced by laser cladding" (S. Yang) has been cancelled as of May 12.

Day-3, May 18, HPL-14 Innovations, #Th4-19

"Enhancement of chain mechanism of combustion by laser-induced excitation of vibration and electronic states of reacting molecules" (A. M. Starik) has been cancelled as of May 8. Due to the above cancellation HPL-14 Session Time will be 17:00-18:00, 60 minutes instead of 17:00-18:20, 80 minutes.

Cancellation

Day-4, May 19, LPM-23 Microprocessing for Semiconductor Industry, #Fr2-1, Invited Talk
"Advanced laser machining technology and systems for semiconductor manufacturing"
(A. Boyle) has been cancelled as of May 11.

Day-4, May 19, LPM SPECIAL SESSION SP L3-3, #Fr1-12
"Fabrication of bioactive HA/Ti composite coating by laser cladding" (S. Yang) has been cancelled as of May 12.

Session Chairs Changed

Day-1, May 16, Tuesday, HPL-01 Analysis of Process Phenomenon
D. Petring, Fraunhofer Institute for Laser Technology, Germany
→ M. Kutsuna, Nagoya Univ., Japan

Day-3, May 18, HPL-10 Surface Treatment 1
E. W. Kreuz, Lehrstuhl für Lasertechnik RWTH-Aachen, Germany
→ J. Gottmann, Lehrstuhl für Lasertechnik RWTH-Aachen, Germany

Day-3, May 18, HPL-12 Surface Treatment 3
M. Kutsuna, Nagoya Univ., Japan
→ K. Uenishi, Osaka Univ., Japan

Day-3, May 18, LPM-22 Manufacture of Photonic Devices
J. Nishii, AIST, Japan
→ W. Watanabe, AIST, Japan

Day-4, May 19, HPL-17 Plastic Joining
K. Yamashita, TOYOBO Ltd., Japan
→ Y. Kawahito, Osaka Univ., Japan

Day-4, May 19, LPM-24 Microprocessing for Electronics Industry I
A. Boyle, Xsil Ltd., Ireland
→ To be announced

Co-Authors Deleted

Day-2, May 17, Poster Session, WeP-2
"High peak power pulse amplification using polarization maintaining double clad fiber"
Co-authors, N. Hayasaka, Y. Shimobeppu, Fujitsu Limited, Japan have been deleted.
Please see the revised abstract enclosed.

Typo

Authors Index

W. Watababe → W. Watanabe